

## Silicone Thermal Fiberglass / XK-F20

### Introduction

Unlike traditional low thermal conductivity fiberglass with ceramic powder filler, XK-F series is a composite of high performance ceramic filler and 30um thin fiberglass, achieving high thermal conductivity on flat surface with low pressure. Recommended for TO220/TO3P where insulation is needed.

### Features

Elastomeric compound coated on both sides  
 No oil bleed, long term stability  
 Electrical insulating

### Applications

Power supplies  
 Automotive electronics  
 Motor controls  
 Power semiconductors



	unit	XK-F20	Method
Reinforcement Carrier		Fiberglass	visual
Color		Pink	
Thickness	mm	0.2-0.38	ASTM D374
Specific Gravity	g/cm <sup>3</sup>	2.7	ASTM D792
Hardness	Shore A	75	ASTM D2240
Thermal impedance	°Cin <sup>2</sup> /W	0.28	ASTM D5470
Thermal Conductivity	W/mK	2.2	HOT DISK
Volume Resistivity	Ωcm	>10 <sup>13</sup>	ASTM D257
Breakdown Voltage	KV	>3.5	ASTM D149
Dielectric Constant	1	7	ASTM D150
Application temperature	°C	-50~220	
Tensile strength	psi	>300	ASTM D149
Elongation	%	<10	ASTM D149
Siloxane Volatiles D4~D20	%	<0.01	GC-FID
Flammability	UL94	V-0	UL94